

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
6 October 2005 (06.10.2005)

PCT

(10) International Publication Number  
**WO 2005/093826 A1**

(51) International Patent Classification<sup>7</sup>: **H01L 23/02**,  
27/14

(21) International Application Number:  
PCT/JP2005/005999

(22) International Filing Date: 23 March 2005 (23.03.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
2004-093628 26 March 2004 (26.03.2004) JP  
2004-281895 28 September 2004 (28.09.2004) JP

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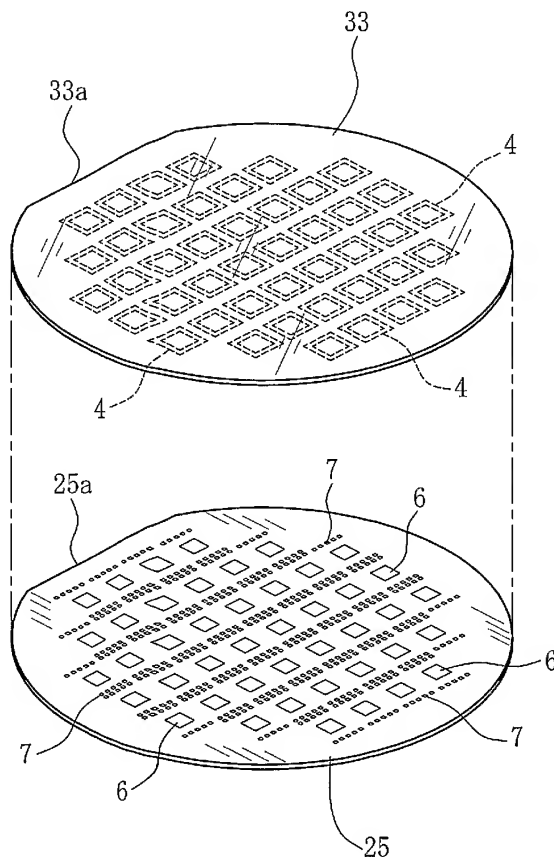
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(81) Designated States (unless otherwise indicated, for every  
kind of national protection available): AE, AG, AL, AM,  
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,  
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,  
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG,

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(54) Title: DEVICE AND METHOD FOR JOINING SUBSTRATES



(57) Abstract: A device for joining substrates (11) is provided inside a clean booth (12). a single axis robot (46) and a five axis robot (47) convey a wafer (25) and a glass substrate (33). A transcribing station (91) obtains a transcribing film (112) on which adhesive is applied from a film supplying section (113), and presses the transcribing film (112) to the glass substrate (33) so as to transcribe the adhesive to the glass substrate (33). A peeling station (92) peels the transcribing film (112) from the glass substrate (33). A joining station (57) positions the wafer (25) and the glass substrate (33), adjusts parallelism of joining surfaces of the wafer (25) and the glass substrate (33), and joins these substrates together. Since the handling and the joining of the wafer (25), the glass substrate (33) and the transcribing film (112) are performed in the clean booth, it is prevented that a yield ratio of the product decreases because of the adhesion of foreign matters.

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KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**(84) Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

**Published:**

— with international search report

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